

# SSM3J01T

Power Management Switch  
High Speed Switching Applications

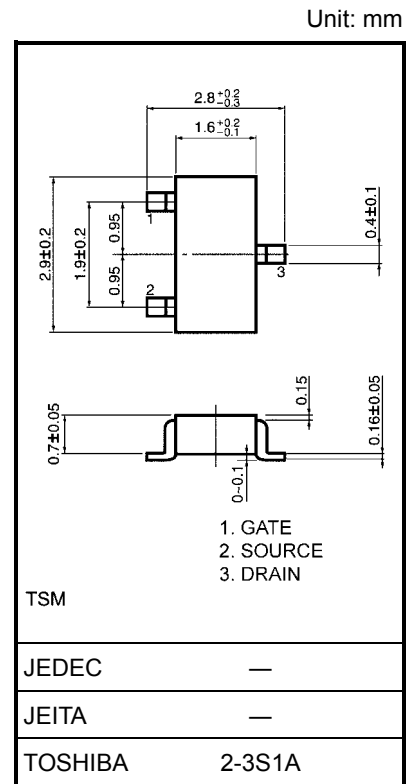
- Small Package
- Low on Resistance:  $R_{on} = 0.4 \Omega$  (max) (@ $V_{GS} = -4 V$ )  
:  $R_{on} = 0.6 \Omega$  (max) (@ $V_{GS} = -2.5 V$ )
- Low Gate Threshold Voltage

## Maximum Ratings (Ta = 25°C)

Characteristic	Symbol	Rating	Unit
Drain-Source voltage	$V_{DS}$	-30	V
Gate-Source voltage	$V_{GSS}$	±10	V
Drain current	DC	$I_D$	-1.7
	Pulse	$I_{DP}$ (Note2)	-3.4
Drain power dissipation (Ta = 25°C)	$P_D$ (Note1)	1250	mW
Channel temperature	$T_{ch}$	150	°C
Storage temperature range	$T_{stg}$	-55~150	°C

Note 1: Mounted on FR4 board  
(25.4 mm × 25.4 mm × 1.6 t, Cu pad: 645 mm<sup>2</sup>, t = 10 s)

Note 2: The pulse width limited by max channel temperature.



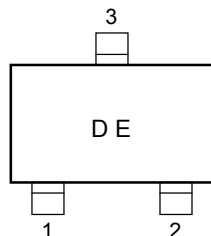
Weight: 10 mg (typ.)

## Handling Precaution

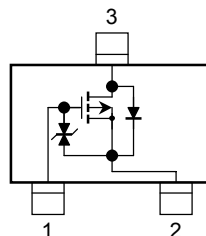
When handling individual devices (which are not yet mounted on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

The Channel-to-Ambient thermal resistance  $R_{th(ch-a)}$  and the drain power dissipation  $P_D$  vary according to the board material, board area, board thickness and pad area, and are also affected by the environment in which the product is used. When using this device, please take heat dissipation fully into account.

## Marking



## Equivalent Circuit



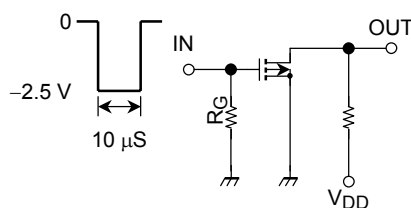
## Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		$I_{GSS}$	$V_{GS} = \pm 10\text{ V}, V_{DS} = 0$	—	—	$\pm 1$	$\mu\text{A}$
Drain-Source breakdown voltage		$V_{(BR)DSS}$	$I_D = -1\text{ mA}, V_{GS} = 0$	-30	—	—	V
Drain Cut-off current		$I_{DSS}$	$V_{DS} = -30\text{ V}, V_{GS} = 0$	—	—	-1	$\mu\text{A}$
Gate threshold voltage		$V_{th}$	$V_{DS} = -3\text{ V}, I_D = -0.1\text{ mA}$	-0.6	—	-1.1	V
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = -3\text{ V}, I_D = -0.85\text{ A}$ (Note3)	1.2	2.3	—	S
Drain-Source ON resistance		$R_{DS(ON)}$	$I_D = -0.85\text{ A}, V_{GS} = -4\text{ V}$ (Note3)	—	0.3	0.4	$\Omega$
Drain-Source ON resistance		$R_{DS(ON)}$	$I_D = -0.85\text{ A}, V_{GS} = -2.5\text{ V}$ (Note3)	—	0.4	0.6	$\Omega$
Input capacitance		$C_{iss}$	$V_{DS} = -10\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	—	240	—	pF
Reverse transfer capacitance		$C_{rss}$	$V_{DS} = -10\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	—	24	—	pF
Output capacitance		$C_{oss}$	$V_{DS} = -10\text{ V}, V_{GS} = 0, f = 1\text{ MHz}$	—	94	—	pF
Switching time	Turn-on time	$t_{on}$	$V_{DD} = -15\text{ V}, I_D = -0.3\text{ A}$	—	36	—	ns
	Turn-off time	$t_{off}$	$V_{GS} = 0 \sim -2.5\text{ V}, R_G = 4.7\ \Omega$	—	37	—	

Note3: Pulse test

## Switching Time Test Circuit

### (a) Test circuit



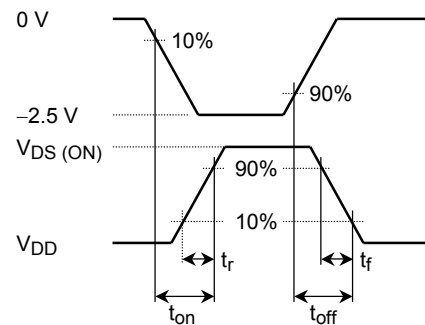
$V_{DD} = -15\text{ V}$   
 $R_G = 4.7\ \Omega$   
 D.U.  $\leq 1\%$   
 $V_{IN}: t_r, t_f < 5\text{ ns}$   
 COMMON SOURCE  
 $T_a = 25^\circ\text{C}$

### (b) $V_{IN}$

$V_{GS}$

### (c) $V_{OUT}$

$V_{DS}$



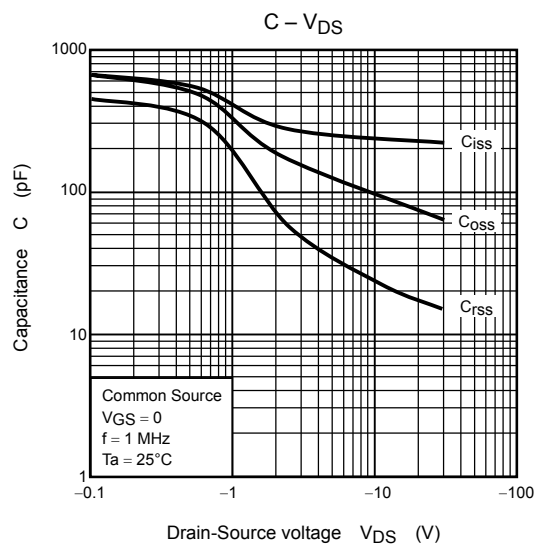
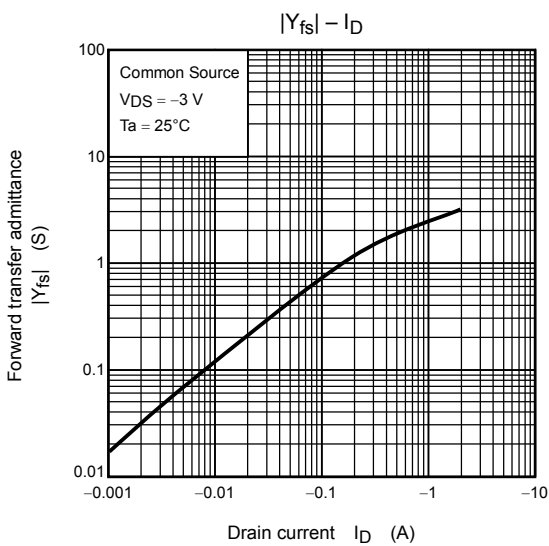
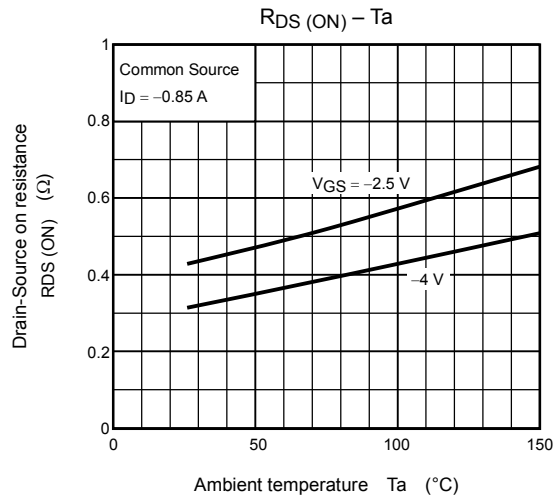
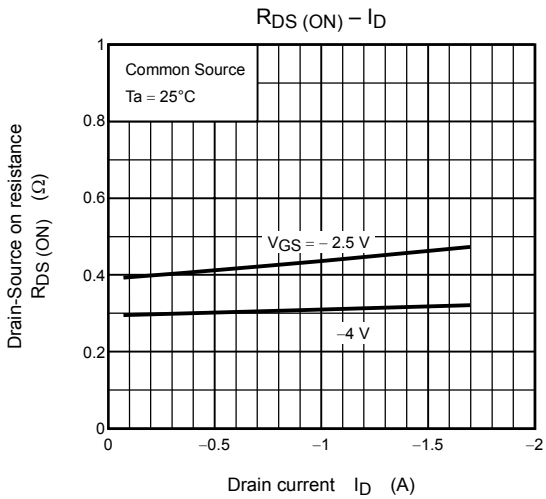
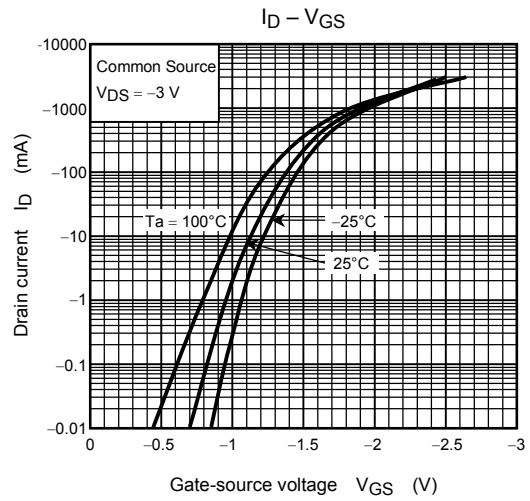
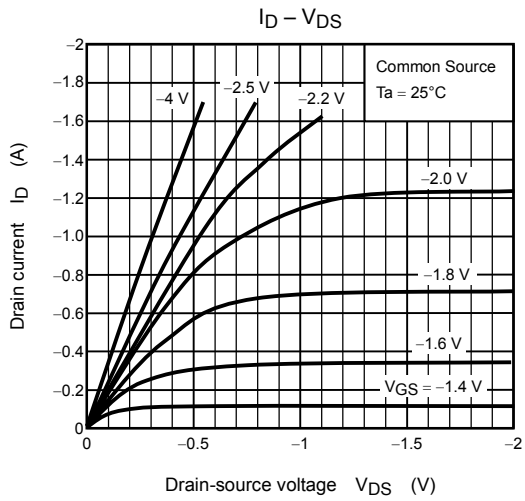
## Precaution

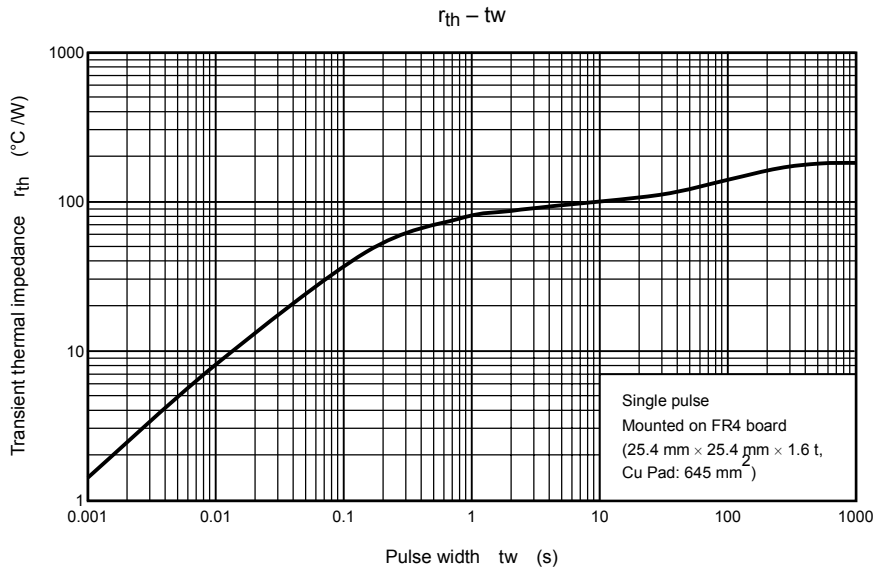
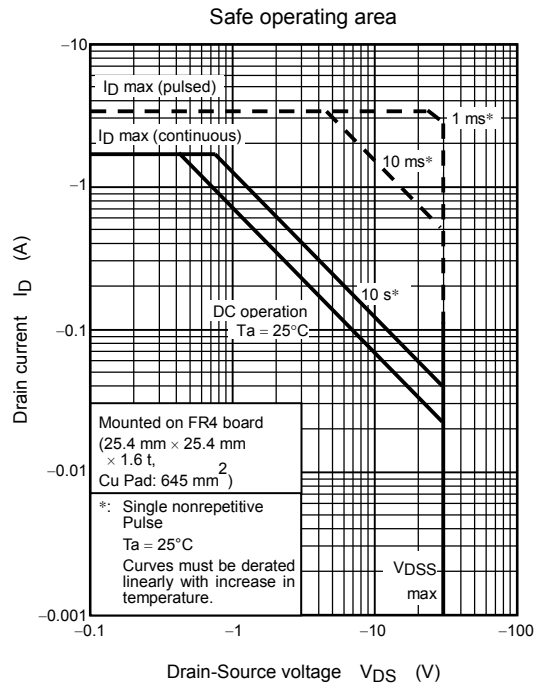
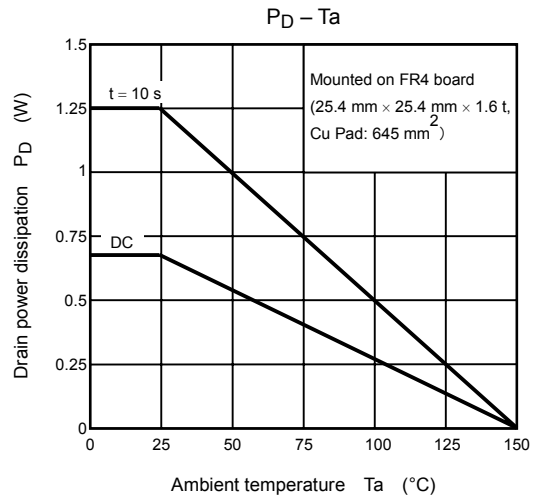
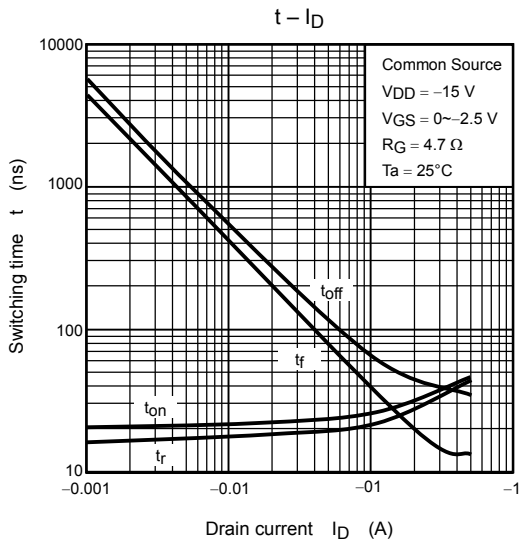
$V_{th}$  can be expressed as voltage between gate and source when low operating current value is  $I_D = -100\ \mu\text{A}$  for this product. For normal switching operation,  $V_{GS(ON)}$  requires higher voltage than  $V_{th}$  and  $V_{GS(OFF)}$  requires lower voltage than  $V_{th}$ .

(relationship can be established as follows:  $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$ )

Please take this into consideration for using the device.

$V_{GS}$  recommended voltage of  $-2.5\text{ V}$  or higher to turn on this product.





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